Sensors and Materials

Special Issue on Innovations in Multimodal Sensing

for Intelligent Devices, Systems, and Applications

Call for Papers

Multimodal sensing combines diverse sensors (optical, acoustic, mechanical, chemical) to enhance the accuracy and adaptability of intelligent systems in complex environments. This drives innovations in sensor hardware, materials, and multimodal data fusion methods.

For this special issue, we seek innovative research on multimodal sensing technologies and their integration into intelligent applications. We invite contributions on novel sensor devices (physical, mechanical, optical, chemical, or biological), advances in sensor materials and fabrication techniques, and data fusion methods for multisensor integration. Submissions showcasing real-world applications in fields such as industrial automation, robotics, medical diagnostics, biotechnology, and environmental monitoring are encouraged. We hope to pursue new developments with these papers.

Scope:

- Novel multimodal sensor designs
- Innovative sensing materials and fabrication techniques
- Vision-language signal processing and multimodal sensors
- Data fusion techniques in reliable sensors and systems
- Integrated sensors and Internet of Things
- Sensor behavior and associated phenomena in multimodal systems
- Applications in intelligent multimodal sensing, such as
  - Industrial automation and smart manufacturing
  - Medical diagnostics and healthcare monitoring
  - Robotics, autonomous vehicles, and drone systems
  - Biotechnology, wearable biosensors, and life science research
  - Environmental monitoring, smart agriculture, and climate sensing

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